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(54) **CHIP PACKAGE STRUCTURE, PRODUCTION METHOD FOR CHIP PACKAGE STRUCTURE, AND ELECTRONIC DEVICE**

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(57) **ABSTRACT**

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The technology of this application relates to a chip package structure, a production method for a chip package structure, and an electronic device. The chip package structure includes a first connection layer having an upper surface and a lower surface that are opposite to each other, a die disposed on the upper surface of the first connection layer, a first conduction structure disposed on an upper surface of the die, a first plastic package layer covering the die and the first conduction structure, and a rewiring layer disposed on the first plastic package layer. At least a part of the first conduction structure is exposed from an upper surface of the first plastic package layer. The rewiring layer is coupled to the first conduction structure. A signal of the die can be directly led out through the first conduction structure and the rewiring layer.

